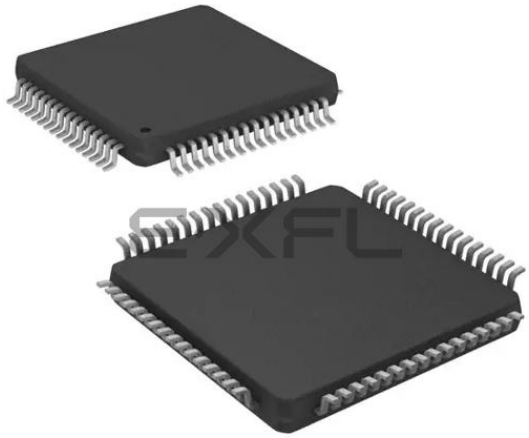
Microchip Technology - DSPIC33EP512MC506T-E/PT Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

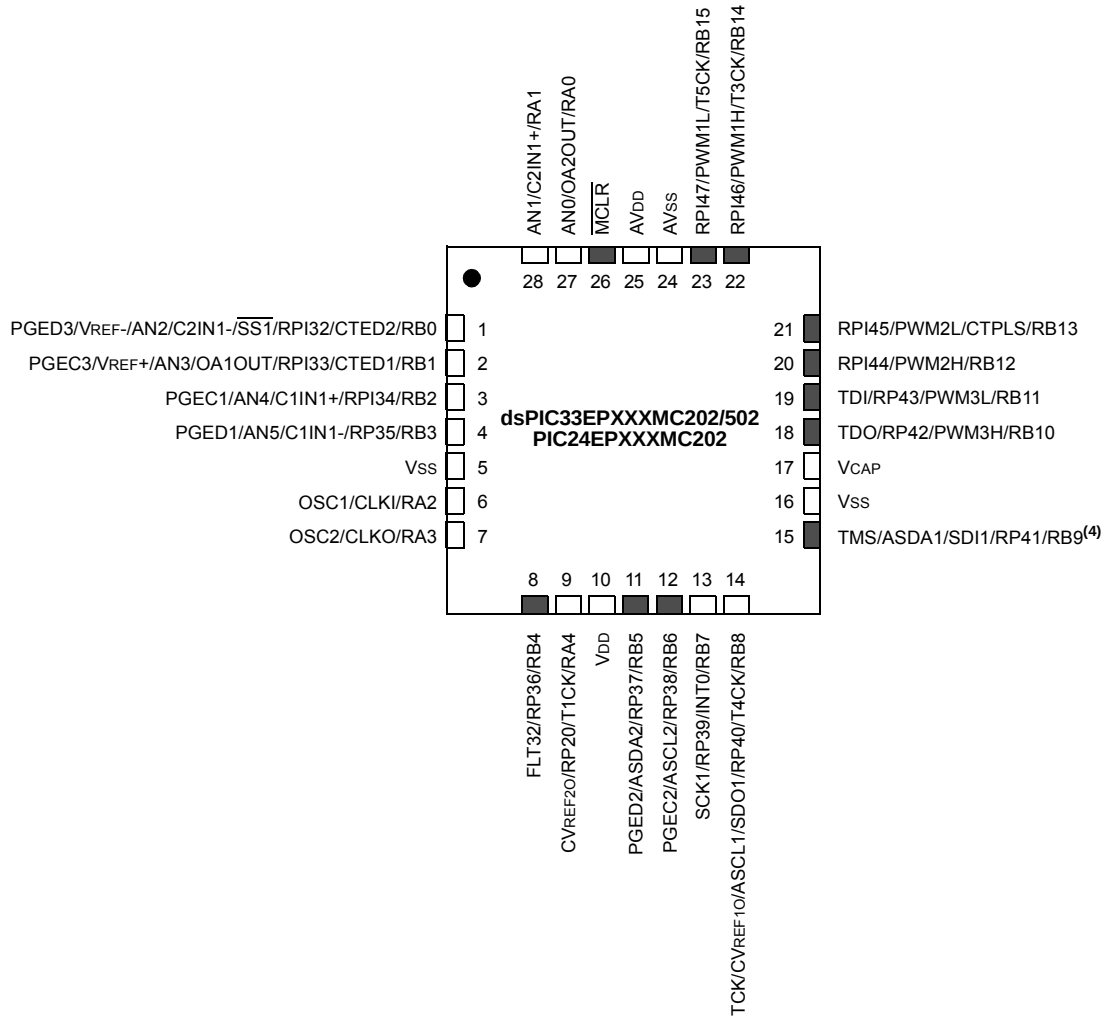
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc506t-e-pt

Pin Diagrams (Continued)

28-Pin QFN-S(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name(4)	Pin Type	Buffer Type	PPS	Description
AN0-AN15	I	Analog	No	Analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA	I	ST	Yes	Compare Fault A input (for Compare channels).
OCFB	I	ST	No	Compare Fault B input (for Compare channels).
OC1-OC4	O	—	Yes	Compare Outputs 1 through 4.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
RA0-RA4, RA7-RA12	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC13, RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD5, RD6, RD8	I/O	ST	No	PORTD is a bidirectional I/O port.
RE12-RE15	I/O	ST	No	PORTE is a bidirectional I/O port.
RF0, RF1	I/O	ST	No	PORTF is a bidirectional I/O port.
RG6-RG9	I/O	ST	No	PORTG is a bidirectional I/O port.
T1CK	I	ST	No	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	No	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
CTPLS	O	ST	No	CTMU pulse output.
CTED1	I	ST	No	CTMU External Edge Input 1.
CTED2	I	ST	No	CTMU External Edge Input 2.
$\overline{U1CTS}$	I	ST	No	UART1 Clear-To-Send.
$\overline{U1RTS}$	O	—	No	UART1 Ready-To-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
BCLK1	O	ST	No	UART1 IrDA® baud clock output.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name(4)	Pin Type	Buffer Type	PPS	Description
C1IN1- C1IN2- C1IN1+ OA1OUT C1OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 1 Negative Input 1. Comparator 1 Negative Input 2. Op Amp/Comparator 1 Positive Input 1. Op Amp 1 output. Comparator 1 output.
C2IN1- C2IN2- C2IN1+ OA2OUT C2OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 2 Negative Input 1. Comparator 2 Negative Input 2. Op Amp/Comparator 2 Positive Input 1. Op Amp 2 output. Comparator 2 output.
C3IN1- C3IN2- C3IN1+ OA3OUT C3OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 3 Negative Input 1. Comparator 3 Negative Input 2. Op Amp/Comparator 3 Positive Input 1. Op Amp 3 output. Comparator 3 output.
C4IN1- C4IN1+ C4OUT	I I O	Analog Analog —	No No Yes	Comparator 4 Negative Input 1. Comparator 4 Positive Input 1. Comparator 4 output.
CVREF1O CVREF2O	O O	Analog Analog	No No	Op amp/comparator voltage reference output. Op amp/comparator voltage reference divided by 2 output.
PGED1 PGEC1 PGED2 PGEC2 PGED3 PGEC3	I/O I I/O I I/O I	ST ST ST ST ST ST	No No No No No No	Data I/O pin for Programming/Debugging Communication Channel 1. Clock input pin for Programming/Debugging Communication Channel 1. Data I/O pin for Programming/Debugging Communication Channel 2. Clock input pin for Programming/Debugging Communication Channel 2. Data I/O pin for Programming/Debugging Communication Channel 3. Clock input pin for Programming/Debugging Communication Channel 3.
$\overline{\text{MCLR}}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.
VREF+	I	Analog	No	Analog voltage reference (high) input.
VREF-	I	Analog	No	Analog voltage reference (low) input.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS AND MICROCONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

TABLE 4-23: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1BUFPNT1	0420	F3BP<3:0>				F2BP<3:0>				F1BP<3:0>				F0BP<3:0>				0000
C1BUFPNT2	0422	F7BP<3:0>				F6BP<3:0>				F5BP<3:0>				F4BP<3:0>				0000
C1BUFPNT3	0424	F11BP<3:0>				F10BP<3:0>				F9BP<3:0>				F8BP<3:0>				0000
C1BUFPNT4	0426	F15BP<3:0>				F14BP<3:0>				F13BP<3:0>				F12BP<3:0>				0000
C1RXM0SID	0430	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM0EID	0432	EID<15:8>								EID<7:0>								xxxx
C1RXM1SID	0434	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM1EID	0436	EID<15:8>								EID<7:0>								xxxx
C1RXM2SID	0438	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM2EID	043A	EID<15:8>								EID<7:0>								xxxx
C1RXF0SID	0440	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF0EID	0442	EID<15:8>								EID<7:0>								xxxx
C1RXF1SID	0444	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF1EID	0446	EID<15:8>								EID<7:0>								xxxx
C1RXF2SID	0448	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF2EID	044A	EID<15:8>								EID<7:0>								xxxx
C1RXF3SID	044C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF3EID	044E	EID<15:8>								EID<7:0>								xxxx
C1RXF4SID	0450	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF4EID	0452	EID<15:8>								EID<7:0>								xxxx
C1RXF5SID	0454	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF5EID	0456	EID<15:8>								EID<7:0>								xxxx
C1RXF6SID	0458	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF6EID	045A	EID<15:8>								EID<7:0>								xxxx
C1RXF7SID	045C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF7EID	045E	EID<15:8>								EID<7:0>								xxxx
C1RXF8SID	0460	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF8EID	0462	EID<15:8>								EID<7:0>								xxxx
C1RXF9SID	0464	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF9EID	0466	EID<15:8>								EID<7:0>								xxxx
C1RXF10SID	0468	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF10EID	046A	EID<15:8>								EID<7:0>								xxxx
C1RXF11SID	046C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Allocating different Page registers for read and write access allows the architecture to support data movement between different pages in data memory. This is accomplished by setting the DSRPAG register value to the page from which you want to read, and configuring the DSWPAG register to the page to which it needs to be written. Data can also be moved from different PSV to EDS pages, by configuring the DSRPAG and DSWPAG registers to address PSV and EDS space, respectively. The data can be moved between pages by a single instruction.

When an EDS or PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the EDS or PSV pages can occur at the page boundaries when:

- The initial address prior to modification addresses an EDS or PSV page
- The EA calculation uses Pre-Modified or Post-Modified Register Indirect Addressing; however, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSxPAG register is incremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. When an underflow is detected, the DSxPAG register is decremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. This creates a linear EDS and PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0, EDS and PSV spaces. Table 4-61 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSxPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-61: OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0, EDS and PSV SPACE BOUNDARIES(2,3,4)

O/U, R/W	Operation	Before			After		
		DSxPAG	DS EA<15>	Page Description	DSxPAG	DS EA<15>	Page Description
O, Read	[++Wn] or [Wn++]	DSRPAG = 0x1FF	1	EDS: Last page	DSRPAG = 0x1FF	0	See **Note 1**
O, Read		DSRPAG = 0x2FF	1	PSV: Last lsw page	DSRPAG = 0x300	1	PSV: First MSB page
O, Read		DSRPAG = 0x3FF	1	PSV: Last MSB page	DSRPAG = 0x3FF	0	See **Note 1**
O, Write		DSWPAG = 0x1FF	1	EDS: Last page	DSWPAG = 0x1FF	0	See **Note 1**
U, Read	[--Wn] or [Wn--]	DSRPAG = 0x001	1	PSV page	DSRPAG = 0x001	0	See **Note 1**
U, Read		DSRPAG = 0x200	1	PSV: First lsw page	DSRPAG = 0x200	0	See **Note 1**
U, Read		DSRPAG = 0x300	1	PSV: First MSB page	DSRPAG = 0x2FF	1	PSV: Last lsw page

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the base Data Space (0x0000-0x8000).

2: An EDS access with DSxPAG = 0x000 will generate an address error trap.

3: Only reads from PS are supported using DSRPAG. An attempt to write to PS using DSWPAG will generate an address error trap.

4: Pseudo-Linear Addressing is not supported for large offsets.

4.5 Instruction Addressing Modes

The addressing modes shown in Table 4-63 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the MAC class of instructions differ from those in the other instruction types.

4.5.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the MUL instruction), which writes the result to a register or register pair. The MOV instruction allows additional flexibility and can access the entire Data Space.

4.5.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

```
Operand 3 = Operand 1 <function> Operand 2
```

where Operand 1 is always a working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can either be a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

TABLE 4-63: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 3 **TRIGMODE:** Trigger Status Mode Select bit
- 1 = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
- 0 = TRIGSTAT is cleared only by software

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits
- 111 = Center-Aligned PWM mode: Output set high when OCxTMR = OCxR and set low when OCxTMR = OCxRS(1)
- 110 = Edge-Aligned PWM mode: Output set high when OCxTMR = 0 and set low when OCxTMR = OCxR(1)
- 101 = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
- 100 = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
- 011 = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
- 010 = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
- 001 = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
- 000 = Output compare channel is disabled

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

2: Each Output Compare x module (OCx) has one PTG clock source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO4 = OC1
PTGO5 = OC2
PTGO6 = OC3
PTGO7 = OC4

REGISTER 16-1: PTCON: PWMx TIME BASE CONTROL REGISTER (CONTINUED)

bit 6-4 **SYNCSRC<2:0>:** Synchronous Source Selection bits(1)
111 = Reserved
•
•
•
100 = Reserved
011 = PTGO17(2)
010 = PTGO16(2)
001 = Reserved
000 = SYNCI1 input from PPS

bit 3-0 **SEVTPS<3:0>:** PWMx Special Event Trigger Output Postscaler Select bits(1)
1111 = 1:16 Postscaler generates Special Event Trigger on every sixteenth compare match event
•
•
•
0001 = 1:2 Postscaler generates Special Event Trigger on every second compare match event
0000 = 1:1 Postscaler generates Special Event Trigger on every compare match event

Note 1: These bits should be changed only when PTEN = 0. In addition, when using the SYNCI1 feature, the user application must program the period register with a value that is slightly larger than the expected period of the external synchronization input signal.

2: See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.

NOTES:

REGISTER 17-3: QEI1STAT: QEI1 STATUS REGISTER

U-0	U-0	HS, R/C-0	R/W-0	HS, R/C-0	R/W-0	HS, R/C-0	R/W-0
—	—	PCHEQIRQ	PCHEQIEN	PCLEQIRQ	PCLEQIEN	POSOVIRQ	POSOVIEN
bit 15							bit 8

HS, R/C-0	R/W-0	HS, R/C-0	R/W-0	HS, R/C-0	R/W-0	HS, R/C-0	R/W-0
PCIIRQ(1)	PCIIEN	VELOVIRQ	VELOVIEN	HOMIRQ	HOMIEN	IDXIRQ	IDXIEN
bit 7							bit 0

Legend:	HS = Hardware Settable bit	C = Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **PCHEQIRQ:** Position Counter Greater Than or Equal Compare Status bit
1 = POS1CNT ≥ QEI1GEC
0 = POS1CNT < QEI1GEC

bit 12 **PCHEQIEN:** Position Counter Greater Than or Equal Compare Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 11 **PCLEQIRQ:** Position Counter Less Than or Equal Compare Status bit
1 = POS1CNT ≤ QEI1LEC
0 = POS1CNT > QEI1LEC

bit 10 **PCLEQIEN:** Position Counter Less Than or Equal Compare Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 9 **POSOVIRQ:** Position Counter Overflow Status bit
1 = Overflow has occurred
0 = No overflow has occurred

bit 8 **POSOVIEN:** Position Counter Overflow Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 7 **PCIIRQ:** Position Counter (Homing) Initialization Process Complete Status bit(1)
1 = POS1CNT was reinitialized
0 = POS1CNT was not reinitialized

bit 6 **PCIIEN:** Position Counter (Homing) Initialization Process Complete interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

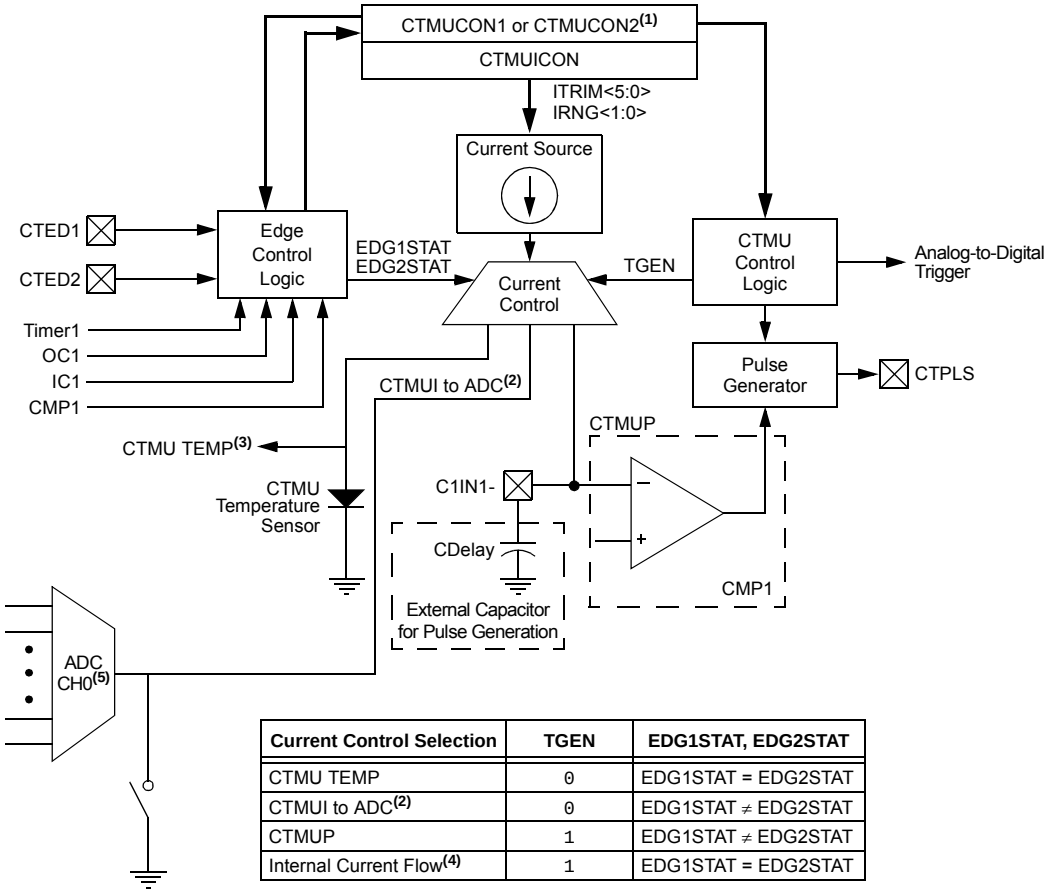
bit 5 **VELOVIRQ:** Velocity Counter Overflow Status bit
1 = Overflow has occurred
0 = No overflow has not occurred

bit 4 **VELOVIEN:** Velocity Counter Overflow Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 3 **HOMIRQ:** Status Flag for Home Event Status bit
1 = Home event has occurred
0 = No Home event has occurred

Note 1: This status bit is only applicable to PIMOD<2:0> modes, '011' and '100'.

FIGURE 22-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	0	EDG1STAT = EDG2STAT
CTMUI to ADC(2)	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
Internal Current Flow(4)	1	EDG1STAT = EDG2STAT

Note 1: When the CTMU is not actively used, set TGEN = 1, and ensure that EDG1STAT = EDG2STAT. All other settings allow current to flow into the ADC or the C1IN1- pin. If using the ADC for other purposes besides the CTMU, set IDISSEN = 0. If IDISSEN is set to '1', it will short the output of the ADC CH0 MUX to VSS.

2: CTMUI connects to the output of the ADC CH0 MUX. When CTMU current is steered into this node, the current will flow out through the selected ADC channel determined by the CH0 MUX (see the CH0Sx bits in the AD1CHS0 register).

3: CTMU TEMP connects to one of the ADC CH0 inputs; see CH0SA and CH0SB (AD1CHS0<12:8,4:0).

4: If TGEN = 1 and EDG1STAT = EDG2STAT, CTMU current source is still enabled and may be shunted to VSS internally. This should be considered in low-power applications.

5: The switch connected to ADC CH0 is closed when IDISSEN (CTMUCON1<9>) = 1, and opened when IDISSEN = 0.

22.1 CTMU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

22.1.1 KEY RESOURCES

- **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 23-3: AD1CON3: ADC1 CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC4(1)	SAMC3(1)	SAMC2(1)	SAMC1(1)	SAMC0(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS7(2)	ADCS6(2)	ADCS5(2)	ADCS4(2)	ADCS3(2)	ADCS2(2)	ADCS1(2)	ADCS0(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** ADC1 Conversion Clock Source bit
1 = ADC internal RC clock
0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** ADC1 Conversion Clock Select bits(2)
11111111 = TP • (ADCS<7:0> + 1) = TP •256 = TAD
•
•
•
00000010 = TP • (ADCS<7:0> + 1) = TP •3 = TAD
00000001 = TP • (ADCS<7:0> + 1) = TP •2 = TAD
00000000 = TP • (ADCS<7:0> + 1) = TP •1 = TAD

Note 1: This bit is only used if SSRC<2:0> (AD1CON1<7:5>) = 111 and SSRCG (AD1CON1<4>) = 0.
2: This bit is not used if ADRC (AD1CON3<15>) = 1.

FIGURE 25-4: USER-PROGRAMMABLE BLANKING FUNCTION BLOCK DIAGRAM

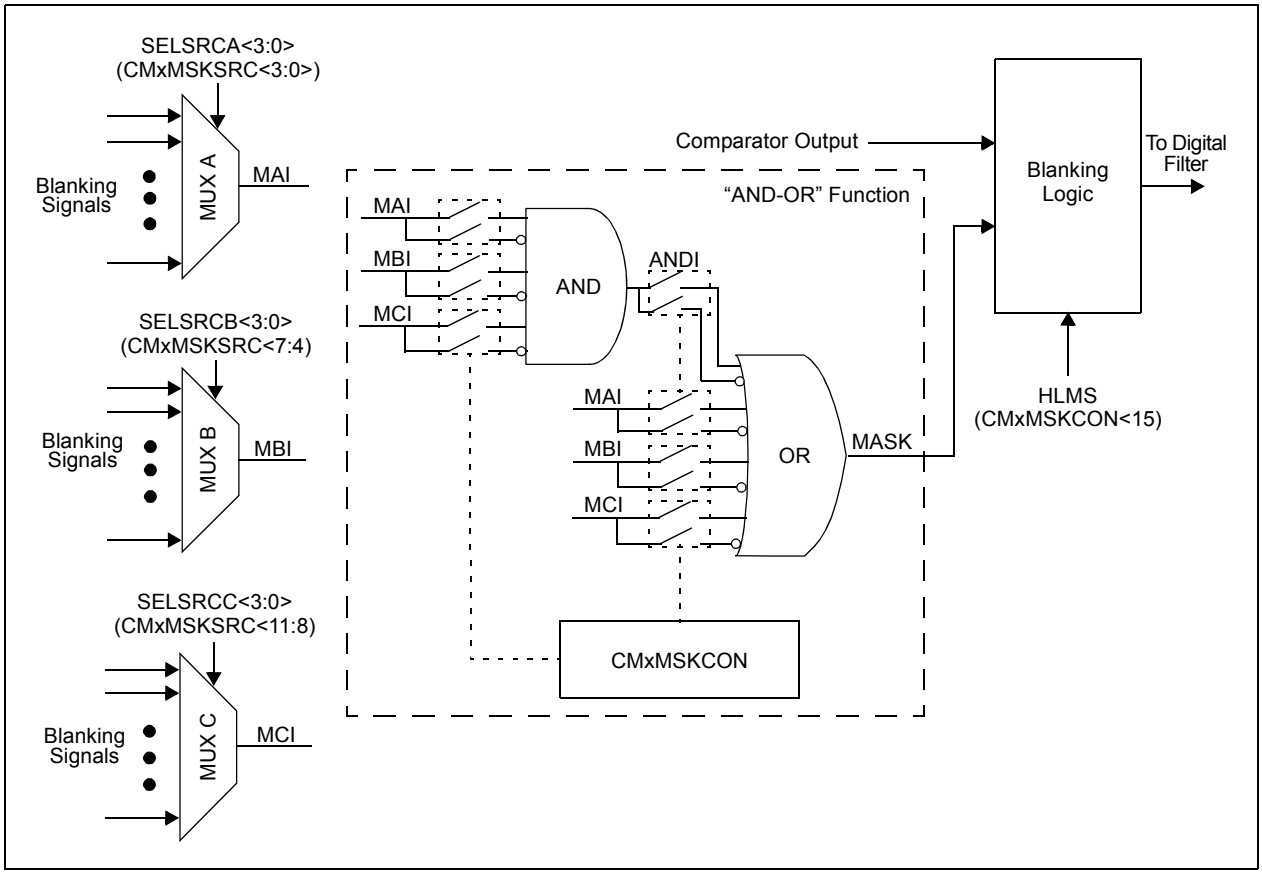
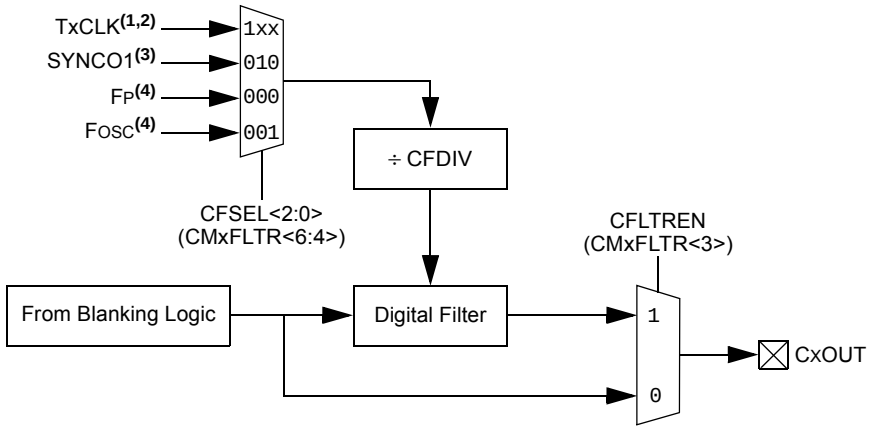


FIGURE 25-5: DIGITAL FILTER INTERCONNECT BLOCK DIAGRAM



Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

REGISTER 25-4: CMxMSKSRC: COMPARATOR x MASK SOURCE SELECT CONTROL REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	RW-0
—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-8 **SELSRCC<3:0>:** Mask C Input Select bits

1111 = FLT4
1110 = FLT2
1101 = PTGO19
1100 = PTGO18
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM3H
0100 = PWM3L
0011 = PWM2H
0010 = PWM2L
0001 = PWM1H
0000 = PWM1L

bit 7-4 **SELSRCB<3:0>:** Mask B Input Select bits

1111 = FLT4
1110 = FLT2
1101 = PTGO19
1100 = PTGO18
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM3H
0100 = PWM3L
0011 = PWM2H
0010 = PWM2L
0001 = PWM1H
0000 = PWM1L

NOTES:

REGISTER 27-1: DEVID: DEVICE ID REGISTER

R	R	R	R	R	R	R	R
DEVID<23:16>(1)							
bit 23							bit 16

R	R	R	R	R	R	R	R
DEVID<15:8>(1)							
bit 15							bit 8

R	R	R	R	R	R	R	R
DEVID<7:0>(1)							
bit 7							bit 0

Legend:	R = Read-Only bit	U = Unimplemented bit

bit 23-0 **DEVID<23:0>:** Device Identifier bits(1)

Note 1: Refer to the *"dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70663) for the list of device ID values.

REGISTER 27-2: DEVREV: DEVICE REVISION REGISTER

R	R	R	R	R	R	R	R
DEVREV<23:16>(1)							
bit 23							bit 16

R	R	R	R	R	R	R	R
DEVREV<15:8>(1)							
bit 15							bit 8

R	R	R	R	R	R	R	R
DEVREV<7:0>(1)							
bit 7							bit 0

Legend:	R = Read-only bit	U = Unimplemented bit

bit 23-0 **DEVREV<23:0>:** Device Revision bits(1)

Note 1: Refer to the *"dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70663) for the list of device revision values.

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: VOH – 4x DRIVER PINS

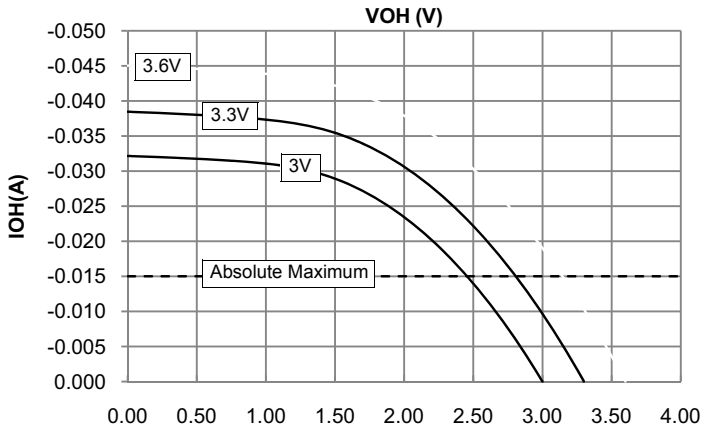


FIGURE 32-2: VOH – 8x DRIVER PINS

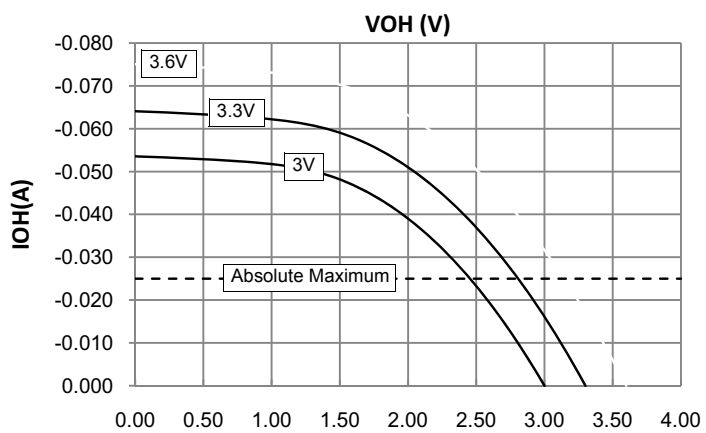


FIGURE 32-3: VOL – 4x DRIVER PINS

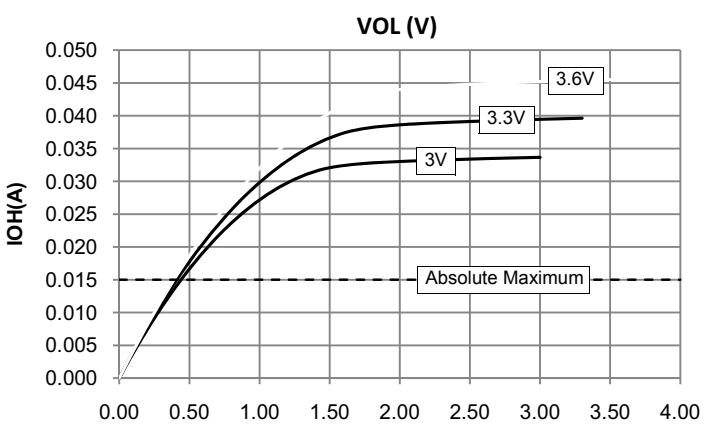
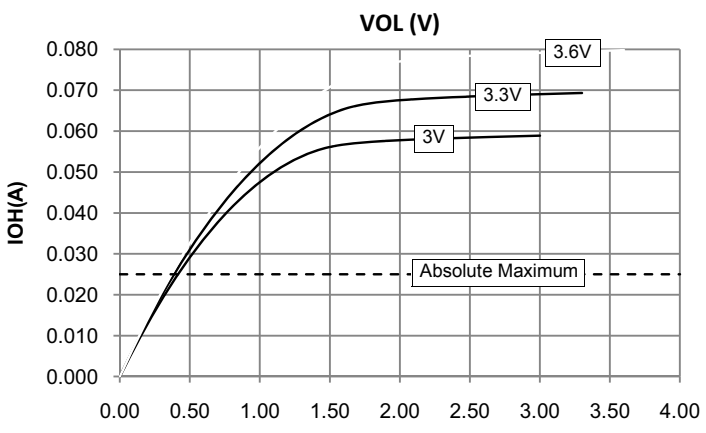
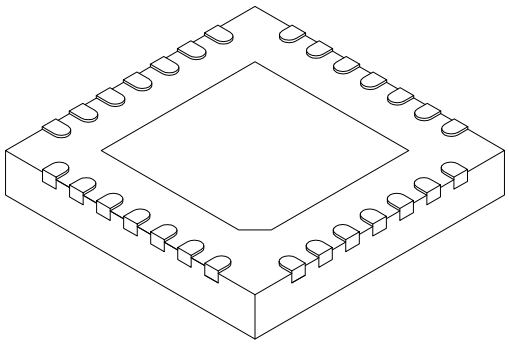


FIGURE 32-4: VOL – 8x DRIVER PINS



28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.70
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124C Sheet 2 of 2

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings(1). Removed Parameter DC18 (VCORE) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4). Updated Note 1 in the DC Characteristics: Operating Current (IDD) (see Table 30-6). Updated Note 1 in the DC Characteristics: Idle Current (IIDLE) (see Table 30-7). Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (IPD) (see Table 30-8). Updated Note 1 in the DC Characteristics: Doze Current (IDOZE) (see Table 30-9). Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12). Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated Internal FRC Accuracy Parameter F20a (see Table 30-21). Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).
Section 31.0 "Packaging Information"	Updated packages by replacing references of VLAP with TLA.
"Product Identification System"	Changed VLAP to TLA.